



## Final Product Change Notification

202106007F01 : Assembly Site Transfer from TFME to ASECL for SOICN8 Package

**Note:** This notice is NXP Company Proprietary.

**Issue Date:** Jun 24, 2021 **Effective date:** Sep 22, 2021 

Here is your personalized notification about a NXP general announcement.  
For detailed information we invite you to [view this notification online](#)

### Change Category

- |  |  |  |   |   |
|--|--|--|---|---|
| <input type="checkbox"/> Wafer Fab Process   | <input type="checkbox"/> Assembly Process              | <input type="checkbox"/> Product Marking           | <input type="checkbox"/> Test Process   | <input type="checkbox"/> Design                         |
| <input type="checkbox"/> Wafer Fab Materials | <input checked="" type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification  | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Errata                         |
| <input type="checkbox"/> Wafer Fab Location  | <input checked="" type="checkbox"/> Assembly Location  | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Location  | <input type="checkbox"/> Electrical spec./Test coverage |
| <input type="checkbox"/> Firmware            | <input type="checkbox"/> Other                         |  |   |   |

## PCN Overview

### Description

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NXP Semiconductor is announcing the assembly site transfer for package SOICN8 from TongFu Microelectronics Co.,Ltd, Nantong, China (TFME) Assembly Facility to ASE-CL, CHUNG-LI, TAIWAN (ASECHUNG) Assembly Facility.

The change in assembly site also includes change in Lead frame , molding compound and epoxy.

### Reason

TongFu Microelectronics Co.,Ltd, Nantong, China(TFME) assembly facility will not support SOICN8 package assembly, assembly site will be transferred to ASE-CL, CHUNG-LI, TAIWAN (ASECHUNG) for supplier assurance.

### **Identification of Affected Products**

Top Side Marking

There is no change to orderable part number.  
Change in package trace code is explained under the 'Remarks' section below.

### **Product Availability**

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#### **Sample Information**

Samples are available upon request

Samples with part number PC9S08QD2MSC will be provided upon request.

#### **Production**

Planned first shipment Sep 24, 2021

### **Anticipated Impact on Form, Fit, Function, Reliability or Quality**

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No Impact on form, fit, function, reliability or quality

#### **Data Sheet Revision**

No impact to existing datasheet

#### **Disposition of Old Products**

Existing inventory will be shipped until depleted

### **Additional information**

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Self qualification: [view online](#)

Additional documents: [view online](#)

### **Timing and Logistics**

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In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Jul 24, 2021.

## Remarks

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The assembly site is reflected in the package trace code.  
The format for the NXP standard trace code:  
SOICN8: ALYWZ or LYWZ

A=Assembly Location, L=Wafer Lot, YW=Date Code, Z =Assembly Lot Split,  
The marking for TFME is A=XN.  
The marking for ASECL is A=X.

## Contact and Support

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For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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NXP Quality Management Team.

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